

BRCS020N04RA

Rev.C Mar.-2023

/ Descriptions

TO-220 N
N-CHANNEL MOSFET in a TO-220 Plastic Package.

/ Features

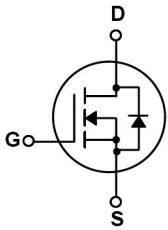
Ultra Low On-Resistance, fast switching, HF Product.

/ Applications

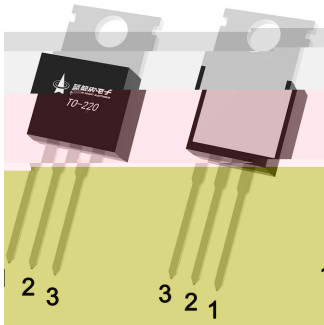
PFC

These devices are well suited for high efficient switched mode power supplies Active power factor correction, electronic lamp ballast based on half bridge topology.

/ Equivalent Circuit



/ Pinning



PIN1 G

PIN 2 4 D

PIN 3 S

/ Marking

See Marking Instructions.

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit	
Drain-Source Voltage	V_{DSS}	40	V	
Drain Current	$I_D(T_C=25)$	220	A	
Pulsed Drain Current	I_{DM}	800	A	
Gate-Source Voltage	V_{GS}	± 20	V	
Single Pulsed Avalanche Energy L=0.5mH	E_{AS}	482	mJ	
Avalanche Current	I_{AS}	35	A	
Total Power Dissipation	$P_D(T_C=25)$	187	W	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150		
Thermal Resistance-Junction to Ambient	t 10s	R_{JA}	15	/W
	Steady-State		60	
Thermal Resistance-Junction to Case	Steady-State	R_{JC}	0.67	

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V$ $I_D=250\mu A$	40	44		V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=40V$ $V_{GS}=0V$			1	μA
Gate-Body Leakage Current Forward	I_{GSS}	$V_{GS}=\pm 20V$ $V_{DS}=0V$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=250\mu A$	1	1.6	3	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V$ $I_D=20A$		1.6	2	m
		$V_{GS}=4.5V$ $I_D=10A$		2.1	4	
Forward On Voltage	V_{SD}	$V_{GS}=0V$ $I_S=1A$			1.2	V
Input Capacitance	C_{iss}	$V_{DS}=25V$ $V_{GS}=0V$ $f=1MHz$		11000		pF
Output Capacitance	C_{oss}			840		
Reverse Transfer Capacitance	C_{rss}			650		

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DATA SHEET

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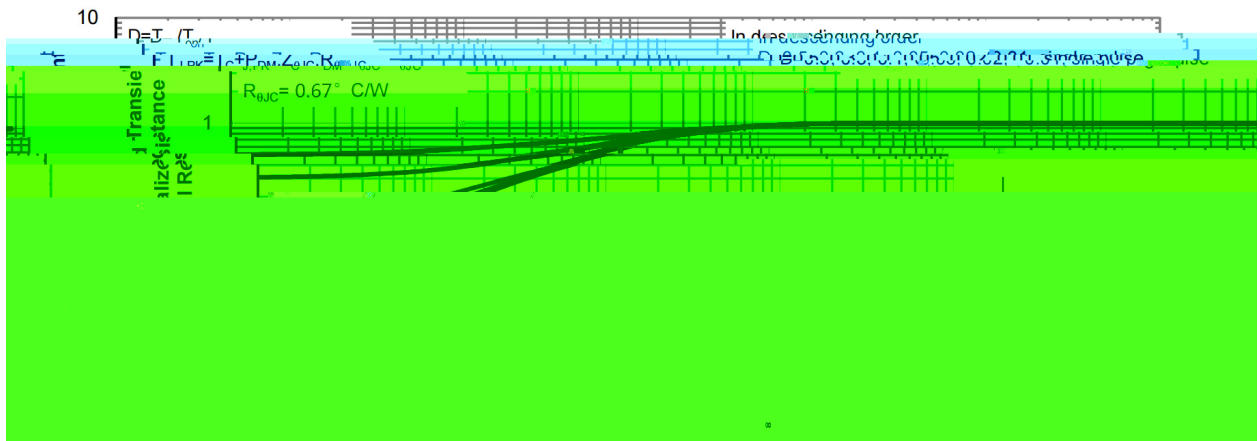
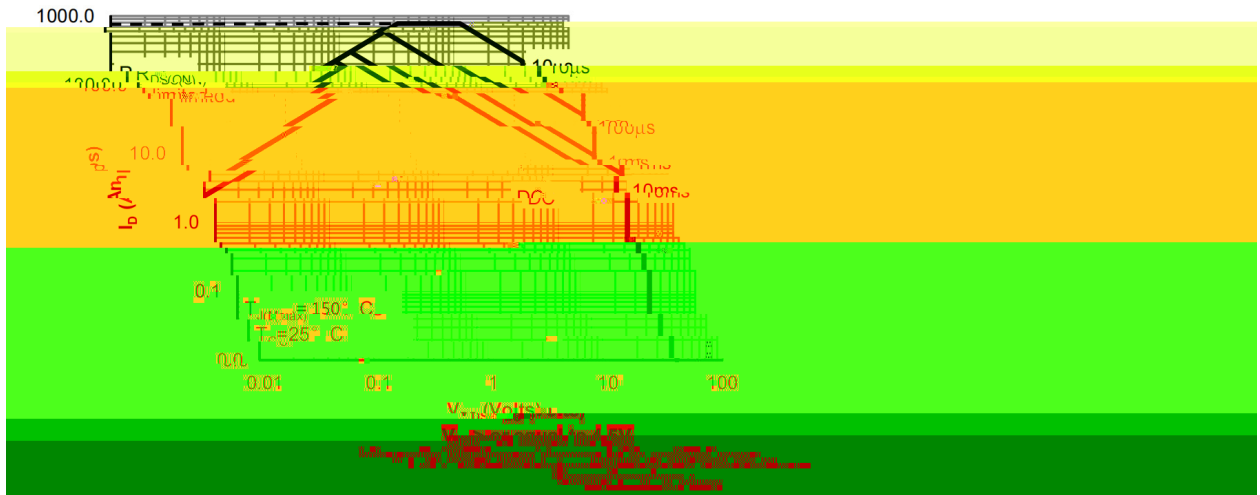
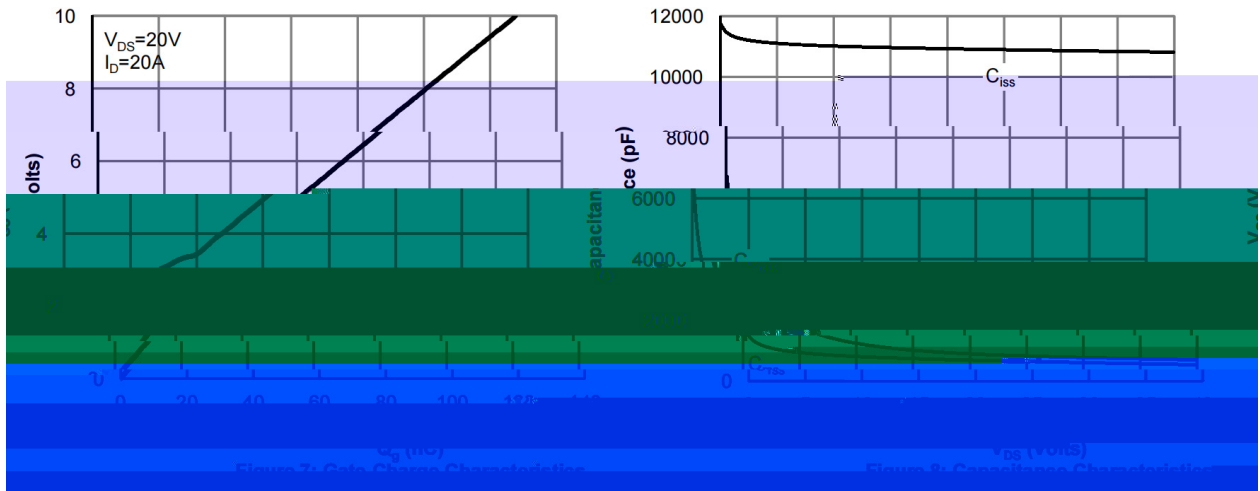
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T72e52.26 35492485.852-18.06 refoQ.777 .852 Q(T72e57.66 354924)74.66-18.06 refoBT/T84 1 Tf10.4958 0 0 10

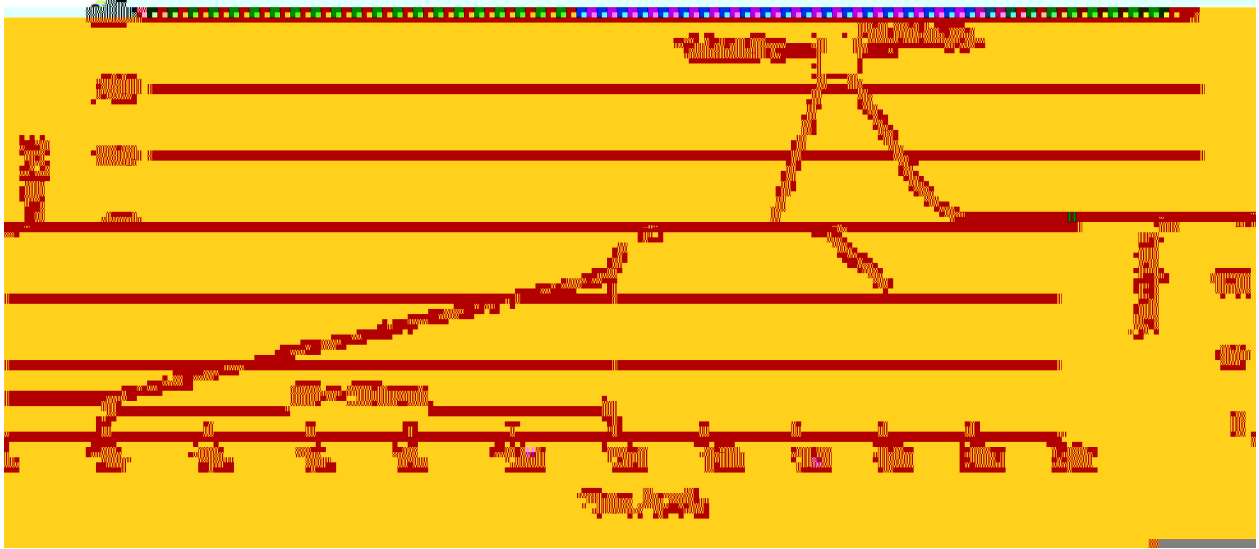


DATA SHEET

/ Electrical Characteristic Curve



() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | |
|---|--------|-----------|---|
| 1 | 25 150 | 60 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255±5 | 5±0.5sec; | 2.Peak Temp.:255±5 , Duration:5±0.5sec. |
| 3 | 2 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units					Dimension (unit mm ³)		
	Units/Bag /	Bags/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Bag	Inner Box	Outer Box
TO-220/F	200	10	2,000	5	10,000	135x190	237x172x102	560x245x195

/ TUBE

Units/Inner Box —
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